



DDTB (LO-R1) U

PNP PRE-BIASED 500 mA SOT-323 SURFACE MOUNT TRANSISTOR

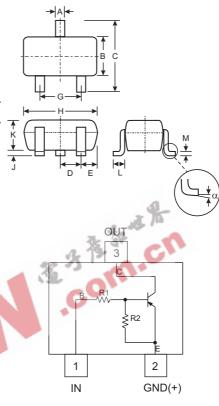
Features

- Epitaxial Planar Die Construction
- Complementary NPN Types Available (DDTD)
- Built-In Biasing Resistors
- Lead Free/RoHS Compliant (Note 2)
- "Green" Device (Note 3 & 4)

Mechanical Data

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe)
- Marking: Date Code and Type Code, See Page 2
- Ordering Information (See Page 2)
- Weight: 0.006 grams (approximate)

P/N	R1 (NOM)	R2 (NOM)	Type Code
DDTB122LU	0.22KΩ	10KΩ	P75
DDTB142JU	0.47KΩ	10KΩ	P76
DDTB122TU	0.22KΩ	OPEN	P77
DDTB142TU	0.47KΩ	OPEN	P78



SOT-323									
Dim	Dim Min								
Α	0.25	0.40							
В	1.15 1.35								
С	2.00 2.20								
D	0.65 Nominal								
Е	0.30 0.40								
G	1.20	1.40							
н	1.80 2.20								
J	0.0 0.10								
к	0.90	1.00							
L	0.25	0.40							
М	0.10	0.18							
α	0°	8°							
All Din	nensions	in mm							

Schematic and Pin Configuration

Maximum Ratings @ T_A = 25°C unless otherwise specified

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Characteris	tic	Symbol	Value	Unit
Supply Voltage, (3) to (2)		V _{CC}	-50	V
Input Voltage, (1) to (2) DDTB122LU DDTB142JU		V _{IN}	+5 to -6 +5 to -6	V
Input Voltage, (2) to (1) DDTB122TU DDTB142TU		V _{EBO (MAX)}	-5	V
Output Current	All	Ι _C	-500	mA
Power Dissipation (Note 1)		Pd	200	mW
Thermal Resistance, Junction to Ar	nbient Air (Note 1)	R _{0JA}	625	°C/W
Operating and Storage and Temper	rature Range	T _j , T _{STG}	-55 to +150	°C

Note: 1. Mounted on FR4 PC Board with recommended pad layout at http://www.diodes.com/datasheets/ap02001.pdf.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



NEW PRODUCT

Electrical Characteristics @ $T_A = 25^{\circ}C$ unless otherwise specified

R1, R2 Types

			1	1	1	1	
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
Input Voltage	DDTB122LU DDTB142JU	V _{l(off)}	-0.3 -0.3	_	_	V	$V_{CC}=-5V,\ I_O=-100\mu A$
	DDTB122LU DDTB142JU	V _{l(on)}			-2.0 -2.0	V	$V_{O} = -0.3V, I_{O} = -20mA$ $V_{O} = -0.3V, I_{O} = -20mA$
Output Voltage		V _{O(on)}		_	-0.3V	V	$I_0/I_1 = -50 \text{mA}/-2.5 \text{mA}$
Input Current DDTB122LU DDTB142JU		lı			-28 -13	mA	V _I = -5V
Output Current		I _{O(off)}		_	-0.5	μA	$V_{CC} = -50V, V_I = 0V$
DC Current Gain DDTB122LU DDTB142JU		Gı	56 56			_	$V_{O} = -5V, I_{O} = -50mA$
Gain-Bandwidth Product*		f⊤		200	—	MHz	$V_{CE} = -10V$, $I_E = -5mA$, f = 100MHz

* Transistor - For Reference Only

Electrical Characterist	ics @ T _A = 25°C	ied	R1-Only Types					
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
Collector-Base Breakdown Voltage	e	BV _{CBO}	-50		—	V	I _C = -50μA	
Collector-Emitter Breakdown Volta	age	BV _{CEO}	-40		_	V	I _C = -1mA	
Emitter-Base Breakdown Voltage DDTB122TU DDTB142TU		BV _{EBO}	-5				I _E = -50μA I _E = -50μA	
Collector Cutoff Current		I _{CBO}	_		-0.5	μA	V _{CB} = -50V	
Emitter Cutoff Current DDTB122TU DDTB142TU		I _{EBO}	36	3_	-0.5 -0.5	μA	$V_{EB} = -4V$	
Collector-Emitter Saturation Voltage	ge	V _{CE(sat)}		~0	-0.3	V	I _C = -50mA, I _B = -2.5mA	
DC Current Transfer Ratio DDTB122TU DDTB142TU		hfe	100 100	250 250	600 600	_	I _C = -5mA, V _{CE} = -5V	
Gain-Bandwidth Product*	fτ	_	200	_	MHz	$V_{CE} = -10V, I_E = 5mA, f = 100MHz$		

* Transistor - For Reference Only

Ordering Information (Note 4 & 5)

Device	Packaging	Shipping
DDTB122LU-7-F	SOT-323	3000/Tape & Reel
DDTB142JU-7-F	SOT-323	3000/Tape & Reel
DDTB122TU-7-F	SOT-323	3000/Tape & Reel
DDTB142TU-7-F	SOT-323	3000/Tape & Reel

Notes: 4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

5. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

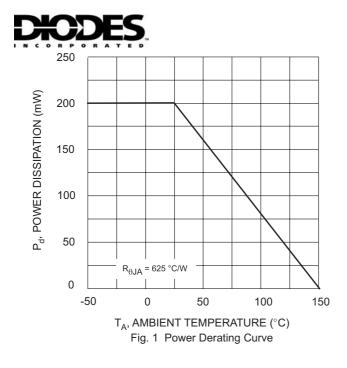
Marking Information

XXX	ΥM

 $\begin{array}{l} XXX = \mbox{Product Type Marking Code} & (\mbox{See Page 1}) \\ YM = \mbox{Date Code Marking} \\ Y = \mbox{Year ex: } T = 2006 \\ M = \mbox{Month ex: } 9 = \mbox{September} \end{array}$

Date Code Key

Year	200	06	2007		2008		2009		2010	2011		2012	
Code	Т		U		V		W		Х	Y		Z	
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec	
Code	1	2	3	4	5	6	7	8	9	0	N	D	



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